

IN THE CLAIMS:

1. (currently amended) A paste composition containing an inorganic filler, a resin and a solvent, wherein the paste composition is characterized in that it contains one or more solvents of which boiling point is 160°C or higher and an inorganic filler of which mean particle diameter is 5 µm or smaller, and the total content of the solvent being 25 wt% or less based on the total amount of the paste composition, and the resin is a thermosetting resin selected from the group consisting of a polyimide resin and an epoxy resin, and when the thermosetting resin is an epoxy resin, the paste composition further contains a curing accelerator or a curing accelerator and a curing agent.

2. (previously presented) A paste composition according to claim 1, wherein the inorganic filler is at least one selected from the group consisting of a barium titanate, a barium zirconate titanate, a strontium titanate, a calcium titanate, a bismuth titanate, a magnesium titanate, a barium neodymium titanate, a barium tin titanate, a barium magnesium niobate, a barium magnesium tantalate, a lead titanate, a lead zirconate, a lead zirconate titanate, a lead niobate, a lead magnesium niobate, a lead nickel

niobate, a lead tungstate, a calcium tungstate, a lead magnesium tungstate, and a titanium dioxide.

3. (original) A paste composition according to claim 1, wherein the inorganic filler contains inorganic fillers of at least two kinds of mean particle diameter, and the greatest mean particle diameter of said mean particle diameters is 0.1-5 μm and is 3 times or more to the minimum mean particle diameter.

4. (original) A paste composition according to claim 1, which contains at least one kind of solvent having an ester structure.

5. (original) A paste composition according to claim 1, which contains at least one kind of solvent having a lactone structure.

6 - 7. (canceled)

8. (original) A paste composition according to claim 1, which contains a compound having a phosphoric ester skeleton.

9. (previously presented) A dielectric composition obtainable by removing solvent from and solidifying the paste composition

described in claim 1, wherein the content of the inorganic filler is 85 to 99 wt% based on the total amount of the solid component contained in the dielectric composition, and a porosity is less than 30 volume %.

10. (previously presented) A dielectric composition according to claim 9, wherein it has a film configuration having a film thickness of 0.5 μm or thicker and 20 μm or thinner.

11. (currently amended) A dielectric composition containing an inorganic filler and a thermosetting resin characterized in that the inorganic filler includes inorganic fillers of at least two kinds of mean particle diameter, and the greatest mean particle diameter of said mean particle diameters is 0.1-5 μm and is 3 times or more to the minimum mean particle diameter, and the thermosetting resin is selected from the group consisting of a polyimide resin and an epoxy resin, and when the thermosetting resin is an epoxy resin, the paste composition further contains a curing accelerator or a curing accelerator and a curing agent.

12. (previously presented) A dielectric composition according to claim 11, wherein the inorganic filler is at least one selected

from the group consisting of a titanium dioxide, a barium titanate, a barium zirconate titanate, a strontium titanate, a calcium titanate, a bismuth titanate, a magnesium titanate, a barium neodymium titanate, a barium tin titanate, a barium magnesium niobate, a barium magnesium tantalate, a lead titanate, a lead zirconate, a lead zirconate titanate, a lead niobate, a lead magnesium niobate, a lead nickel niobate, a lead tungstate, a calcium tungstate and a lead magnesium tungstate.

13. (original) A dielectric composition according to claim 11, wherein, V_f , a volume ratio of the total volume of the inorganic filler to the total volume of the inorganic filler plus the total volume of the solid resin is 50% or more and 95% or less.

14. (canceled)

15. (original) A dielectric composition according to claim 11, wherein said resin is an epoxy resin.

16. (original) A dielectric composition according to claim 11, which contains a compound having a phosphoric ester skeleton.

17. (previously presented) A capacitor comprising an interlayer insulation material obtained by removing the solvent from the paste composition of claim 1.

18. (previously presented) An optical wiring comprising an optical wiring layer obtained by removing the solvent from the paste composition of claim 1.

19. (previously presented) A capacitor comprising the dielectric composition of claim 11.

20. (previously presented) An optical wiring comprising the dielectric composition of claim 11.